

Bill of Materials

TI DESIGNS

TIDC-Bluetooth-Low-Energy-Long-Range

Item	Qty	Reference	Part Description	Manufacturer	Manufacturer Part Number
C_2U2_0402_X5R_M_6p3VDC	2	C1;C2	Capacitor, 2u2, 0402, X5R, +/-20%, 6.3V	Murata	GRM155R60J225ME
C_1N_0402_NP0_J_50	4	C11;C131;C161;C103	Capacitor, 1n, 0402, NP0, 5%, 50V	Murata	GRM1555C1H102JA01D
C_0402	0	C12;C132	Capacitor, general, 0402; Do not mount		
C_10P_0402_NP0_J_50	2	C21;C41	Capacitor, 10p, 0402, NP0, 5%, 50V	Murata	GRM1555C1H100JZ01D
C_1P8_0402_NP0_C_50	2	C22;C42;	Capacitor, 1p8, 0402, NP0, +/-0.25pF 50V	Murata	GRM1555C1H1R8CZ01D
C_100N_0402_X5R_K_10	5	C101;C211;C241;C271;C311	Capacitor, 100n, 0402, X5R, 10%, 10V	Murata	GRM155R71A104KA01D
C_6P8_0402_NP0_C_50	1	C111	Capacitor, 6p8, 0402, NP0, +/-0.25pF 50V	Murata	GRM1555C1H6R8CA01D
C_1P5_0402_NP0_C_50	1	C112	Capacitor, 1p5, 0402, NP0, +/-0.25pF, 50V	Murata	GRM1555C1H1R5CZ01D
C_2P7_0402_NP0_C_50	1	C113	Capacitor, 2p7, 0402, NP0, +/-0.25pF, 50V	Murata	GRM1555C1H2R7CZ01D
C_27P_0402_NP0_J_50	2	C221;C231	Capacitor, 27p, 0402, NP0, 5%, 50V	Murata	GRM1555C1H270JZ01D
C_220P_0402_NP0_J_50	1	C272	Capacitor, 220p, 0402, NP0, 5%, 50V	Murata	GRM1555C1H221JA01D
C_15P_0402_NP0_J_50	2	C321;C331	Capacitor, 15p, 0402, NP0, 5%, 50V	Murata	GRM1555C1H150JA01D
C_1U_0402_X5R_K_6P3	2	C391;C401	Capacitor, 1u, 0402, X5R, 10%, 6.3V	Murata	GRM155R60J105KE19D
L_BEAD_102_0402	2	L1;L2	EMI filter bead, 0402 1k ohms Tape GHz Band Gen Use	Murata	BLM15HG102SN1D
L_1N0_0402_S	2	L21;L41	Inductor, 1n0, 0402, Monolithic type, +/-0.3 nH	Murata	LQG15HS1N0S02D
L_1N0_0402_S	1	L112	Inductor, 1n0, 0402, Monolithic type, +/-0.3 nH	Murata	LQG15HS1N0S02D
L_0402	0	L22 Do not mount	Inductor, general, 0402; Do not mount		
C_18p_0402_NP0_J_50	1	C102	Capacitor, 18p, 0402, NP0, 5% 25V	Murata	GRM1555C1H180JZ01D
L_5N1_0402_S	1	L102	Inductor, 5n1, 0402, +/-0.3 nH	Murata	LQG15HS5N1S02D
L_1N5_0402_B_LQW	1	L111	Inductor, 1n5, 0402, wire-wound type, +/-0.1 nH	Murata	LQW15AN1N5B00D
SMD_SOCKET_2x10	2	P1;P2	SMD pinrow socket, .050 spacing, 2x10	Samtec	SFM-110-02-SM-D-A-K-TR
SMA_SMD	1	P3	SMA connector, straight SMD-mount	Hus-Tsan Group Taiwan	SMA-10V21-TGG
R_0402	0	R11;R12;R13	Resistor, general, 0402; Do not mount		
R_1K0_0402_F	3	R112;R122;R132	Resistor, 1k ohm, 0402, ±1%	Koa	RK73H1ETTP1001F
R_0_0402_3PORT_2-3	1	R111	Resistor 3 ports, 0 ohm, 0402, mounted between pad 2 and pad 3	Koa	RK73Z1ETTP
R_4K3_0402_G	1	R151	Resistor, 4k3 ohms, 0402, 2%	Koa	RK73H1ETTP4301F
R_56K_0402_F	1	R301	Resistor, 56k ohms, 0402, ±1%	Koa	RK73H1ETTP5602F
CC2541	1	U1	2.4 GHz SoC	TI	CC2541
CC2590	1	U2	LNA and PA 10 dBm	TI	CC2590
X_32.000/10/20/60/10	1	X1	Crystal, 32.000000MHz, FA-128, 10.0pF, +/-10ppm, (FTC: +/-20ppm at -40/85C), 60ohms	Epson Toyocom	FA-128, 32MHZ, 10PPM, 10PF, 2x1.6mm, -40/+85C, 60ohms
X_32.768/20/30/40/12.5	1	X2	Crystal, 32.768kHz, FC-12M, 12,5pF	Epson Toyocom	FC-12M, 32.768kHz, 20PPM, 12,5pF

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